Applicants: Ciok Attorney Docket No.: 2003004-US

Serial No.: 10/551,282 Filed: 21 August 2006

Page : 7 of 8

## REMARKS

In the above referenced office action, the Examiner objected to the drawings for failing to show a "protecting layer." Applicant respectfully traverses. For example, Figures 1 and 2 include a remaining edge part 7' that is prepared for adhesive sealing (page 15, line 27). One embodiment includes a protection layer or release layer; thus, element 7' graphically represents various configurations of element(s) that provide a for an edge part prepared for adhesive sealing. Applicant respectfully requests withdrawal of the objections.

The present claims are directed to an ostomy appliance that includes an adhesive wafer to adhere the bag to the patient's skin. The wafer is necessarily coupled with the bag in order to do this. As described in the specification, it is desirable to have access to the side of the wafer that is adhered to the bag for the purpose of measuring the particular patient's stoma dimensions. Thus, the wafer is partially adhered to the bag. Before use, the entirety of the wafer is sealed to the bag. In one embodiment, an adhesive layer is provided that is protected by a release liner. With the release liner in place, the relevant portion of the wafer and the bag are unadhered; thus, the bag can be moved or folded relative to the wafer to permit viewing of the wafer during the measurement process. Once completed, the release liner is removed and the whole wafer becomes bonded to the bag.

The claims have been amended to clarify this arrangement. Namely, a wafer is partially adhered to a bag and an adhesive layer is provided with a barrier or release liner and disposed to fully secure the wafer to the bag.

The claims were rejected under 35 USC 103(a) as being obvious in view of Leise or Thomas. Neither reference teaches or suggests an adhesive that is partially adhered to a bag with another adhesive layer provided with a barrier or release liner and wherein the layer is disposed to fully secure the wafer to the bag. Neither reference is particularly relevant to the claims as amended and Applicant respectfully requests that the rejection be withdrawn.

Applicants: Ciok Attorney Docket No.: 2003004-US

Serial No.: 10/551,282 Filed : 21 August 2006 Page : 8 of 8

## **CONCLUSION**

Applicant respectfully asserts that the pending claims are in condition for allowance and notice of the same is respectfully requested. Should any issues remain outstanding, the Examiner is respectfully urged to telephone the undersigned. No additional fee are believed due at this time; however, the office is authorized to charge any fees actually due and credit any overpayment to deposit account 50-4439.

\* \* \*

Respectfully submitted,

Ciok

Date: 24 March 2009 /Daniel G. Chapik/ Daniel G. Chapik, Reg. No. 43,424 Director and Chief Patent Counsel Coloplast Corp., Coloplast A/S

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